

## Description

The VSM18N03 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

## General Features

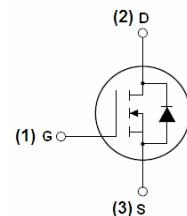
- $V_{DS} = 30V, I_D = 18A$
- $R_{DS(ON)} < 7m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} < 10m\Omega @ V_{GS}=4.5V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized Avalanche voltage and current

## Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



SOP-8



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM18N03-S8	VSM18N03	SOP-8	Ø330mm	12mm	4000 units

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	18	A
Drain Current-Continuous( $T_A=100^\circ C$ )	$I_D (100^\circ C)$	12.7	A
Pulsed Drain Current	$I_{DM}$	72	A
Maximum Power Dissipation	$P_D$	3	W
Single pulse avalanche energy <small>(Note 5)</small>	$E_{AS}$	204	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

## Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	42	°C/W
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**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

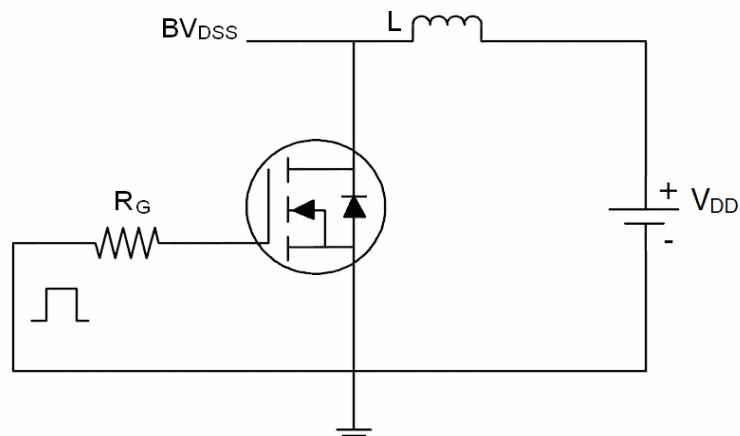
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	30	33	-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=30\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	0.7	1.1	1.4	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=12\text{A}$	-	5.5	7	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=10\text{A}$	-	6.5	10	
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=12\text{A}$	5	-	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	2100	-	PF
Output Capacitance	$\text{C}_{\text{oss}}$		-	460	-	PF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	230	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=10\text{V}, \text{I}_D=12\text{A}$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_{\text{GEN}}=2.7\Omega$	-	20	-	nS
Turn-on Rise Time	$\text{t}_r$		-	15	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	60	-	nS
Turn-Off Fall Time	$\text{t}_f$		-	10	-	nS
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=15\text{V}, \text{I}_D=12\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	41	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	14	-	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	11	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=18\text{A}$	-	-	1.2	V
Diode Forward Current (Note 2)	$\text{I}_s$		-	-	18	A

**Notes:**

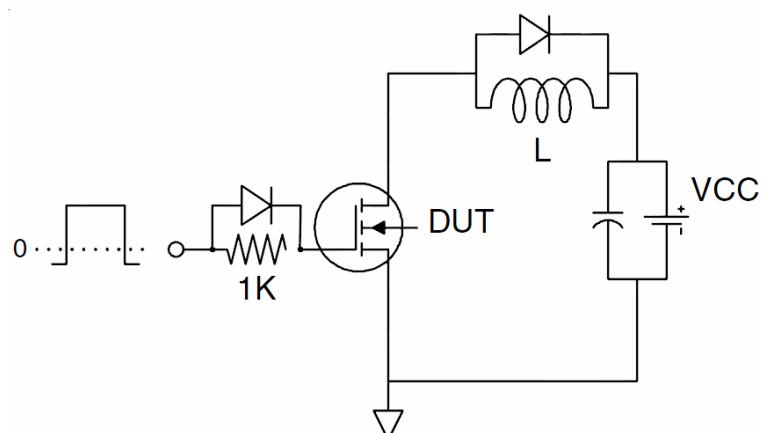
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
  2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
  4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition:  $T_j=25^\circ\text{C}, \text{V}_{\text{DD}}=15\text{V}, \text{V}_{\text{G}}=10\text{V}, \text{L}=0.5\text{mH}, \text{R}_g=25\Omega$

## Test Circuit

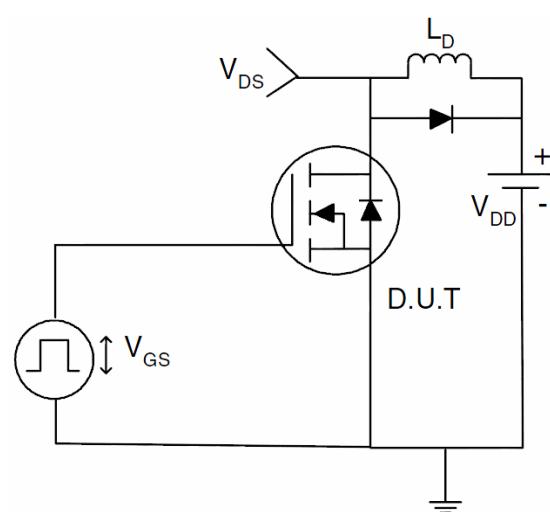
### 1) E<sub>AS</sub> Test Circuits



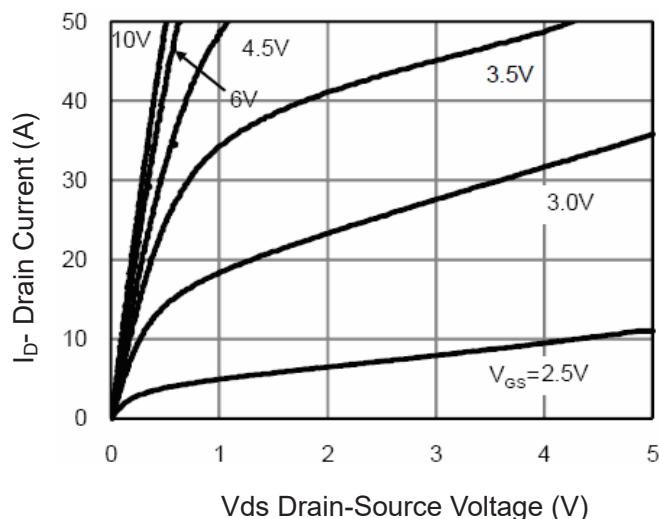
### 2) Gate Charge Test Circuit



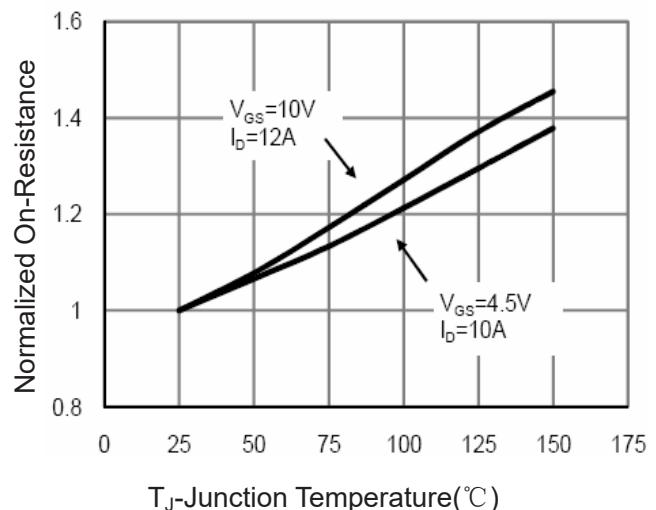
### 3) Switch Time Test Circuit



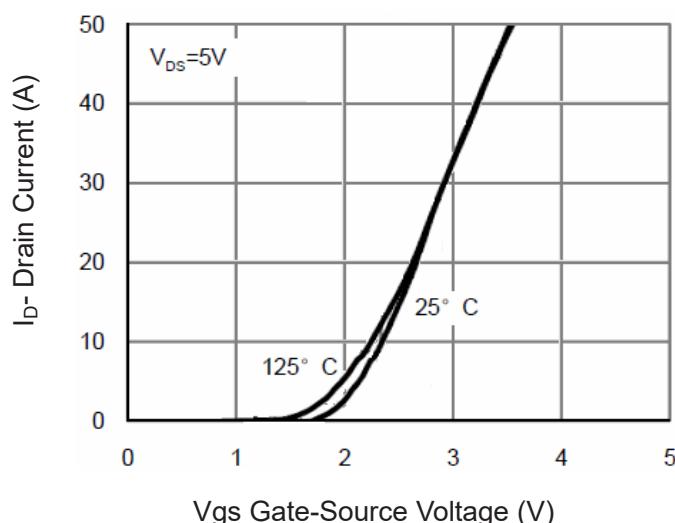
### Typical Electrical and Thermal Characteristics (Curves)



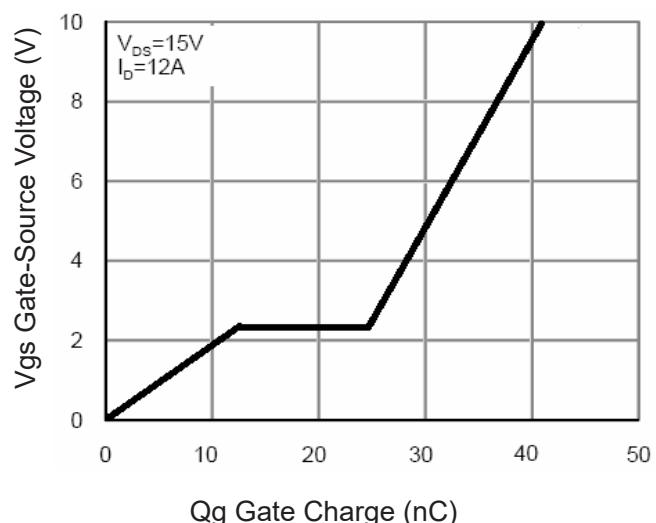
**Figure 1 Output Characteristics**



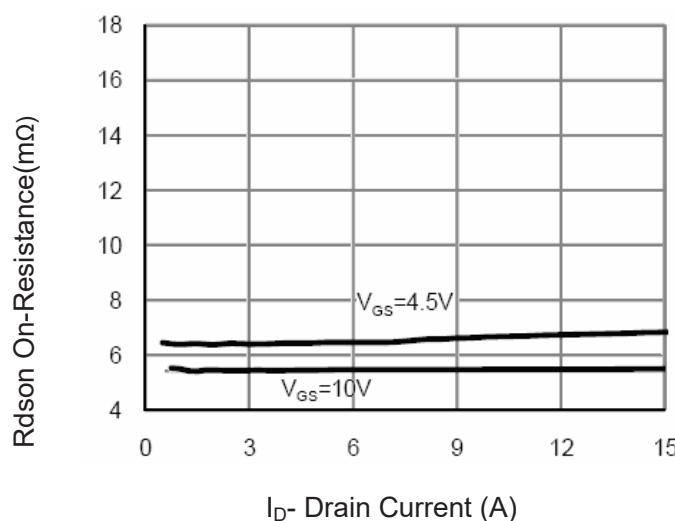
**Figure 4 Rdson-Junction Temperature**



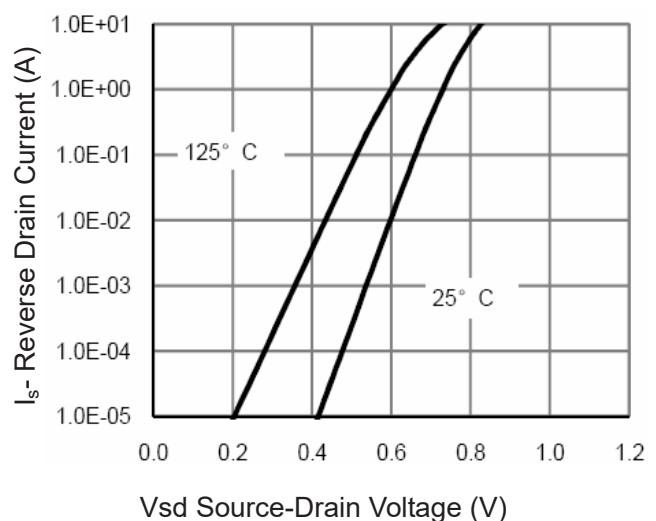
**Figure 2 Transfer Characteristics**



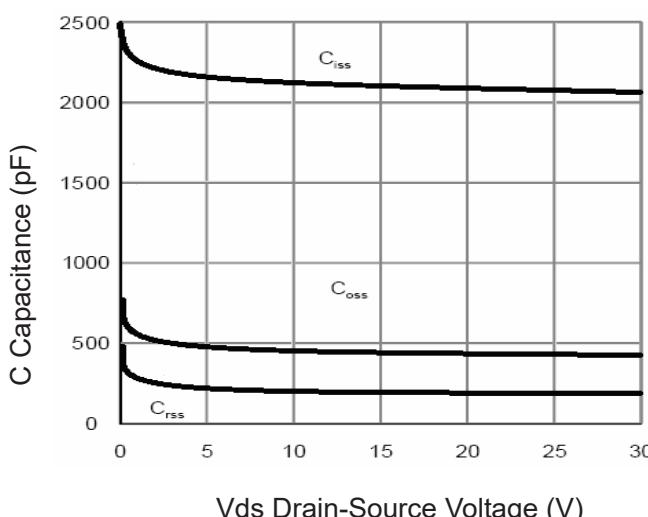
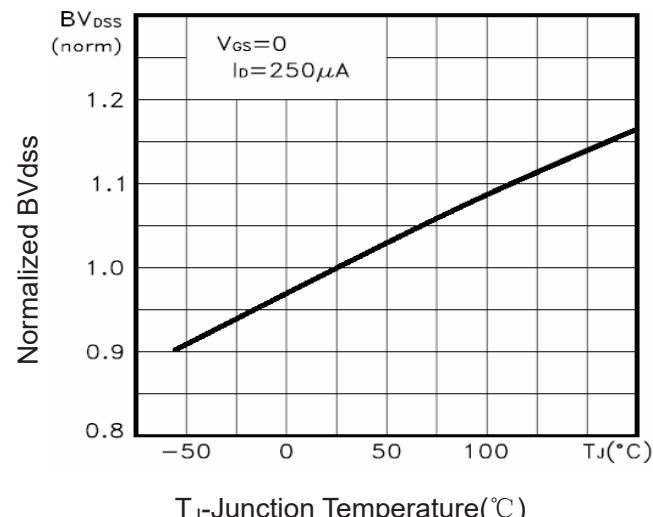
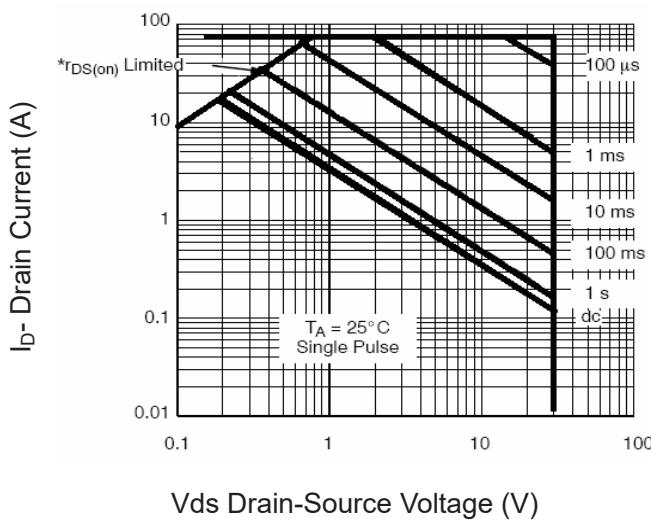
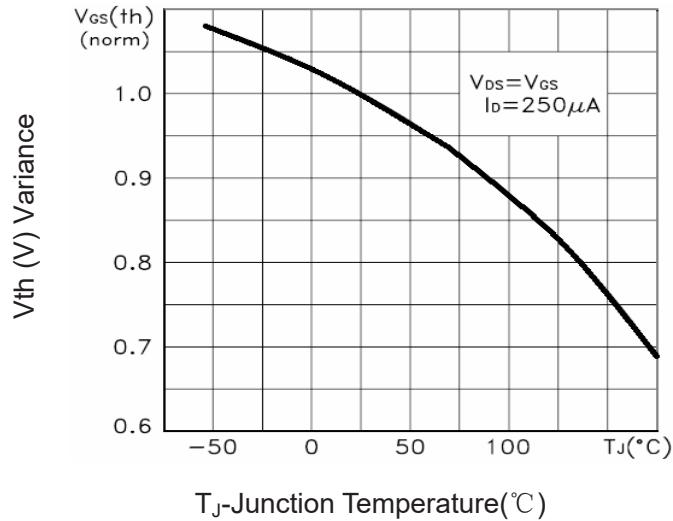
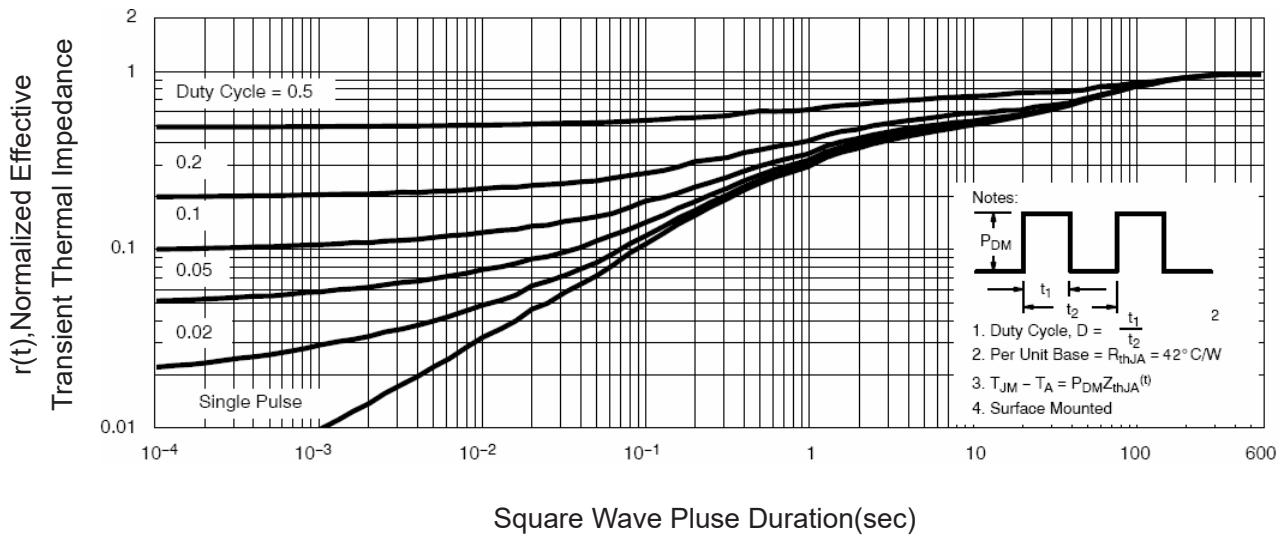
**Figure 5 Gate Charge**



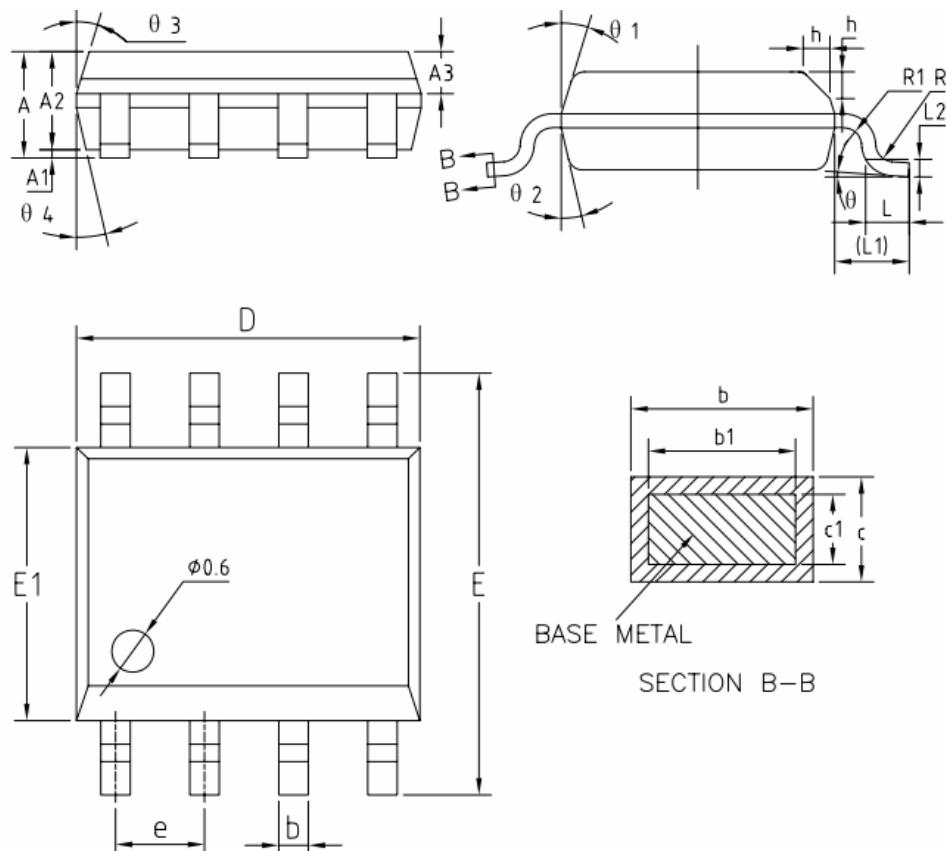
**Figure 3 Rdson- Drain Current**



**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9  $BV_{dss}$  vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10  $V_{gs(th)}$  vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

## SOP-8 Package Information



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.15	0.25
A2	1.25	1.40	1.65
A3	0.50	0.60	0.70
b	0.38	—	0.51
b1	0.37	0.42	0.47
c	0.18	—	0.25
c1	0.17	0.20	0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.17	1.27	1.37
L	0.45	0.60	0.80
L1	1.04REF		
L2	0.25BSC		
R	0.07	—	—
R1	0.07	—	—
h	0.30	0.40	0.50
θ	0°	—	8°
θ1	15°	17°	19°
θ2	11°	13°	15°
θ3	15°	17°	19°
θ4	11°	13°	15°